

PCN Number:	20230323004.1	PCN Date:	March 24, 2023
Title:	Qualification of RFAB as an additional Fab site option for select LBC8 devices		
Customer Contact:	PCN Manager	Dept:	Quality Services
Proposed 1st Ship Date:	Jun 23, 2023	Sample requests accepted until:	Apr 23, 2023*

***Sample requests received after April 23, 2023 will not be supported.**

Change Type:					
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Assembly Materials
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process
<input checked="" type="checkbox"/>	Wafer Fab Site	<input checked="" type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>	Wafer Fab Process
		<input type="checkbox"/>	Part number change		

Notification Details

Description of Change:

Texas Instruments is pleased to announce the qualification of its RFAB fabrication facility as an additional Wafer Fab source for the selected devices listed in the "Product Affected" section.

Current Fab Site			Additional Fab Site		
Current Fab Site	Process	Wafer Diameter	New Fab Site	Process	Wafer Diameter
DP1DM5	LBC8	200 mm	RFAB	LBC8	300 mm

Qual details are provided in the Qual Data Section.

Reason for Change:

Continuity of supply.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

None.

Changes to product identification resulting from this PCN:

Fab Site Information:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
DP1DM5	DM5	USA	Dallas
RFAB	RFB	USA	Richardson

Sample product shipping label (not actual product label)

Product Affected:

BCHW12RHH	PGA300ARHHR	PGA305ARHHR	PGA900ARHHT
BCHW12YZS	PGA300ARHHT	PGA305ARHHT	PGA900AYZSR
DAN001RHH	PGA300CARHHT	PGA900ARHHR	PGA900AYZST

Qualification Report
Approve Date 07-March-2023

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: PGA900ARHHR	QBS Reference (Process): SH8350BCA0PAPG4	QBS Reference (Product, Package): PGA900ARHHR	QBS Reference (Process): PGA302EPWR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	3/231/0	3/231/0	3/231/0
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	3/231/0	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	3/231/0	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	3/231/0	3/231/0	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	3/231/0	3/231/0
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	3/231/0	-	-
HTOL	B1	Life Test	125C	1000 Hours	1/77/0	3/224/0	3/231/0	3/231/0
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	3/2400/0	3/2400/0
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB- Free Solder;	-	-	-	1/22/0	1/22/0
ESD	E2	ESD CDM	-	250 Volts	1/3/0	3/9/0	1/3/0	1/3/0
ESD	E2	ESD HBM	-	1000 Volts	1/3/0	3/9/0	1/3/0	1/3/0
LU	E4	Latch-Up	Per JESD78	-	1/3/0	3/18/0	1/3/0	1/3/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	1/30/0	1/30/0	1/30/0

- QBS: Qual By Similarity
- Qual Device PGA900ARHHR is qualified at MSL2 260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the contact below or your local Field Sales Representative.

Location	E-Mail
WW Change Management Team	PCN_ww_admin_team@list.ti.com

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